

Chip Information

Chip Size	1.25 x 1.25mm
Pad Size	0.99 x 0.99mm
Chip Quantity	6966 pcs/wafer
Scribe Line Width	60um
Passivation	SIN
Wafer Size	5 inch
Top Metallization	Al-Ni-Au (For Solder)

Chip Thickness/Back Metal : See below "Ordering Information"

MAXIMUM RATINGS

Parameter	Symbol	Limit	Unit	Note
Repetitive Peak Reverse Voltage	VRRM	40	V	
Non-Repetitive Peak Reverse Voltage	VRSM		V	
Maximum DC Blocking Voltage	VR		V	
Average Forward Rectified Current	IF(AV)	2	A	
Peak Forward Surge Current	IFSM	50	A	8.3ms Single Half Sine-Wave
Storage and Operating Temperature Range	Tj,TSTG	-65 to +125	degC	

ELECTRICAL CHARACTERISTICS

Parameter	Symbol	Spec Limit	Probe Spec	Typical	Unit	Test Condition	
Maximum Forward Voltage	VF1	0.500		0.460	V	IF=2A	Ta=25degC
	VF2	0.490		0.430	V	IF=1.5A	Ta=25degC
	VF3	0.450		0.410	V	IF=1A	Ta=25degC
	VF4	0.430		0.370	V	IF=0.5A	Ta=25degC
	VF5					V	
Maximum DC Reverse Current	IR1	0.2	0.1	0.012	mA	VR=42V	Ta=25degC
	IR2	0.05	0.02	0.009	mA	VR=30V	Ta=25degC
	IR3			2.5	mA	VR=40V	Ta=100deg
	IR4				mA		
Reverse Breakdown Voltage	BV	42	44	55	V	IR=0.08mA	
Junction Capacitance	Cj				pF		
Reverse Recovery Time	trr				nS		

Ordering Information

Chip Type	Chip Thickness	Back metal
XHJ532	250 +/- 20um	Ti-Ni-Au (For Solder)

Note:

Designed For SR204,B240,RB070M-30